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(54)LASER BONDING METHOD

(57)Abstract:

PURPOSE: To weld a tab lead and a bump with minimum laser energy and reduce the influence of heat to an IC chip by providing a smaller hole through the tab lead than the bump on the IC chip, and bringing the hole and the bump to contact with each other and irradiating the tab lead and the bump with laser light simultaneously.

CONSTITUTION: A hole 11 is provided at a predetermined TAB lead 10 including the therethrough is brought into contact with a bump 13 disposed on an IC chip 12 via a jig. The hole 11 provided through the TAB lead 10 is formed smaller than the bump 13. Once the TAB lead 10 is irradiated with laser light 14 of a spot size greater than the hole 11 in the TAB lead 10 from the upper part, part 15 of the TAB lead 10 and part 16 of the bump 13

are melted to form eutectic, and the TAB lead 10 and the bump 13 are joined.

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